



Product Change Notification - ASER-15HSFK728

Date:

22 May 2020

Product Category:

Broadband Gateway

Affected CPNs:**Notification subject:**

CCB 3886, 3886.001, and 3886.002 Final Notice: Qualification of MMT as an additional assembly site for selected Microsemi products available in 64L VQFN (9x9x1.0mm), 56L VQFN (8x8x1.0mm), & 40L VQFN (6x6x1.0mm) packages.

Notification text:**PCN Status:**

Final notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected Microsemi products available in 64L VQFN (9x9x1.0mm), 56L VQFN (8x8x1.0mm), & 40L VQFN (6x6x1.0mm) packages.

Pre Change:

Assembled at ASEM using PdCu bond wire, CRM1076DS die attach, and CEL-9240HF10AK-G1 mold compound material or assembled at UNIC using CuPdAu bond wire, 8290 die attach, and G770HP mold compound material. Use of bakeable tray packing material in MSL 3 requirements.

Post Change:

Assembled at ASEM using PdCu bond wire, CRM1076DS die attach, and CEL-9240HF10AK-G1 mold compound material, assembled at UNIC using CuPdAu bond wire, 8290 die attach, and G770HP mold compound material, or assembled at MMT using CuPdAu wire material, 3280 die attach, and G700LTD mold compound material. Use of non-bakeable tray packing material in MSL 1 requirements.

Pre and Post Change Summary:

	Pre Change		Post Change		
Assembly Site	ASE Group - Malaysia (ASEM)	Unisem Chengdu Co.,Ltd. (UNIC)	ASE Group - Malaysia (ASEM)	Unisem Chengdu Co.,Ltd. (UNIC)	Microchip Technology Thailand (Branch)



Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

October 24, 2019: Issued initial notification.

November 22, 2019: Reissued initial notification. Corrected Pre and Post Change Attachment to accurately reflect the comparison between the different assembly sites.

May 22, 2019: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on June 22, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN ASER-15HSFK728 Qual Report.pdf](#)

[PCN ASER-15HSFK728 - Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

LE88262TQC
LE88262TQCT
LE88266TQC
LE88266TQCT
LE88286TQC
LE88286TQCT
ZL88103LDF1
ZL88103LDG1
ZL88601LDF1
ZL88601LDG1
ZL88602LDF1
ZL88602LDG1
ZL88701LDF1
ZL88701LDG1
ZL88702LDF1
ZL88702LDG1
ZL88801LDF1
ZL88801LDG1
LE9661WQC
LE9661WQCT
LE9662WQC
LE9662WQCT
LE9672WQC
LE9672WQCT
ZL88105LDF1
ZL88105LDG1
LE9540CUQC
LE9540CUQCT
LE9540DUQC
LE9540DUQCT
LE9541CUQC
LE9541CUQCT
LE9541DUQC
LE9541DUQCT